

Product Information

	Product Number	Tape Thickness w/o liner Mils (mm)	Liner Type	Description	Temperature Resistance		Solvent Resistance	Relative Adhesion		Application Ideas
					Minutes Hours	Days Weeks		HSE	LSE	
Thermally Conductive	9882	2.0 (0.05)	58# PCK	Pressure sensitive acrylic, thermally conductive adhesive.	500°F (260°C)	300°F (149°C)	High	High	Low	Bond heat sinks. Bond rigidizers to flexible circuits.
	9885	5.0 (0.13)								
	9890	10 (0.25)								
Electrically Conductive	9713	3.0 (0.08)	58# PCK	Pressure sensitive acrylic, XYZ-Axis electrically conductive tape.	250°F (121°C)	158°F (70°C)	High	High	Low	EMI/RFI shielding.
	9703	2.0 (0.05)	58# PCK	Pressure sensitive acrylic, Z-Axis electrically conductive tape.						
	7303	2.5 (0.06)	58# PCK	Heat cure epoxy/acrylate hybrid, Z-Axis electrically conductive.	176°F (80°C)	176°F (80°C)	High	High	Low	Bond flex circuits to flex circuits. Bond flex circuit to printed circuit board.
	5303R-1	1.0 (0.025)	2 mil PET	Heat cure cyanate ester, Z-Axis electrically conductive tape.	257°F (125°C)	257°F (125°C)	High	High	Low	Bond flex circuit to flat panel display.
	5303R-2	2.0 (0.05)								Bond flex circuit to PCB.

NOTE: The technical information and data provided here should be considered representative or typical only and should not be used for specification purposes. User should evaluate the 3M product to determine whether it is fit for a particular purpose and suitable for user's method of application.

Relative Adhesion:

HSE – High Surface Energy

LSE – Low Surface Energy

(See p. 28)